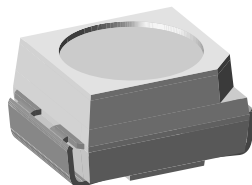


SMD LED in PLCC2 Package



94 8553

FEATURES

- Lead (Pb)-free product - RoHS compliant
- SMD LED with exceptional brightness
- Luminous intensity categorized
- Compatible with automatic placement equipment
- EIA and ICE standard package
- Compatible with IR-Reflow, vapor phase and wave solder processes according to CECC 00802 and J-STD-020C
- Available in 8 mm tape
- Low profile package
- Non-diffused lens: excellent for coupling to light pipes and backlighting
- Low power consumption
- Luminous intensity ratio in one packaging unit $I_{Vmax}/I_{Vmin} \leq 1.6$
- Lead (Pb)-free device
- preconditioning: acc. to JEDEC Level 2a
- ESD-withstand voltage up to 2 kV according to JESD22-A114-B



DESCRIPTION

This device has been designed for applications requiring narrow brightness and color selection.

The package of this device is the PLCC-2.

It consists of a lead frame which is embedded in a white thermoplast. The reflector inside this package is filled up with clear epoxy.

APPLICATIONS

- Automotive: Backlighting in dashboards and switches
- Telecommunication: Indicator and backlighting in telephone and fax
- Indicator and backlight for audio and video equipment
- Indicator and backlight in office equipment
- Flat backlight for LCDs, switches and symbols
- General use

PARTS TABLE

PART	COLOR, LUMINOUS INTENSITY	ANGLE OF HALF INTENSITY ($\pm \varphi$)	TECHNOLOGY
VLMO31J1K2-GS08	Soft orange, $I_V = (4.5 \text{ to } 11.2) \text{ mcd}$	60°	GaAsP on GaP
VLMO31J1K2-GS18	Soft orange, $I_V = (4.5 \text{ to } 11.2) \text{ mcd}$	60°	GaAsP on GaP
VLMO31J1L2-GS08	Soft orange, $I_V = (4.5 \text{ to } 18) \text{ mcd}$	60°	GaAsP on GaP
VLMO31J1L2-GS18	Soft orange, $I_V = (4.5 \text{ to } 18) \text{ mcd}$	60°	GaAsP on GaP
VLMO31K1L2-GS08	Soft orange, $I_V = (7.1 \text{ to } 18) \text{ mcd}$	60°	GaAsP on GaP
VLMO31K1L2-GS18	Soft orange, $I_V = (7.1 \text{ to } 18) \text{ mcd}$	60°	GaAsP on GaP

ABSOLUTE MAXIMUM RATINGS¹⁾, VLMO31..

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage ²⁾		V_R	6	V
DC Forward current	$T_{amb} \leq 60^\circ\text{C}$	I_F	30	mA
Surge forward current	$t_p \leq 10\ \mu\text{s}$	I_{FSM}	0.5	A
Power dissipation		P_V	100	mW
Junction temperature		T_j	100	$^\circ\text{C}$
Operating temperature range		T_{amb}	- 40 to + 100	$^\circ\text{C}$
Storage temperature range		T_{stg}	- 40 to + 100	$^\circ\text{C}$
Soldering temperature	$t \leq 5\ \text{s}$	T_{sd}	260	$^\circ\text{C}$
Thermal resistance junction/ambient	mounted on PC board (pad size > 16 mm ²)	R_{thJA}	400	K/W

Note:

¹⁾ $T_{amb} = 25^\circ\text{C}$ unless otherwise specified²⁾ Driving LED in reverse direction is suitable for short term application**OPTICAL AND ELECTRICAL CHARACTERISTICS¹⁾, VLMO31..., SOFT ORANGE**

PARAMETER	TEST CONDITION	PART	SYMBOL	MIN	TYP.	MAX	UNIT
Luminous intensity ²⁾	$I_F = 10\ \text{mA}$	VLMO31J1K2	I_V	4.5		11.2	mcd
		VLMO31J1L2	I_V	4.5		18	mcd
		VLMO31K1L2	I_V	7.1		18	mcd
Dominant wavelength	$I_F = 10\ \text{mA}$		λ_d	598		611	nm
Peak wavelength	$I_F = 10\ \text{mA}$		λ_p		605		nm
Angle of half intensity	$I_F = 10\ \text{mA}$		φ		± 60		deg
Forward voltage	$I_F = 20\ \text{mA}$		V_F		2.0	2.8	V
Reverse voltage	$I_R = 10\ \mu\text{A}$		V_R	6			V
Junction capacitance	$V_R = 0, f = 1\ \text{MHz}$		C_j		15		pF

Note:

¹⁾ $T_{amb} = 25^\circ\text{C}$ unless otherwise specified²⁾ in one Packing Unit $I_{Vmax}/I_{Vmin} \leq 1.6$ **LUMINOUS INTENSITY CLASSIFICATION**

GROUP	LIGHT INTENSITY [MCD]		
STANDARD	OPTIONAL	MIN	MAX
J	1	4.5	5.6
	2	5.6	7.1
K	1	7.1	9.0
	2	9.0	11.2
L	1	11.2	14.0
	2	14.0	18.0
M	1	18.0	22.4
	2	22.4	28.0

Note:

Luminous intensity is tested at a current pulse duration of 25 ms and an accuracy of $\pm 11\%$.

The above Type Numbers represent the order groups which include only a few brightness groups. Only one group will be shipped on each reel (there will be no mixing of two groups on each reel).

In order to ensure availability, single brightness groups will not be orderable.

In a similar manner for colors where wavelength groups are measured and binned, single wavelength groups will be shipped on any one reel.

In order to ensure availability, single wavelength groups will not be orderable.

CROSSING TABLE

VISHAY	OSRAM
VLMO31J1K2	LOT670-J1K2
VLMO31J1L2	LOT670-J1L2
VLMO31K1L2	LOT670-K1L2

COLOR CLASSIFICATION

GROUP	SOFT ORANGE	
	DOM. WAVELENGTH (NM)	
	MIN.	MAX.
1	598	601
2	600	603
3	602	605
4	604	607
5	606	609
6	608	611

Note:

Wavelengths are tested at a current pulse duration of 25 ms and an accuracy of $\pm 1\ \text{nm}$.

TYPICAL CHARACTERISTICS

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

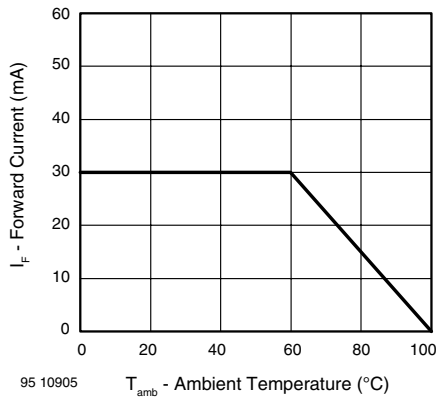


Figure 1. Forward Current vs. Ambient Temperature

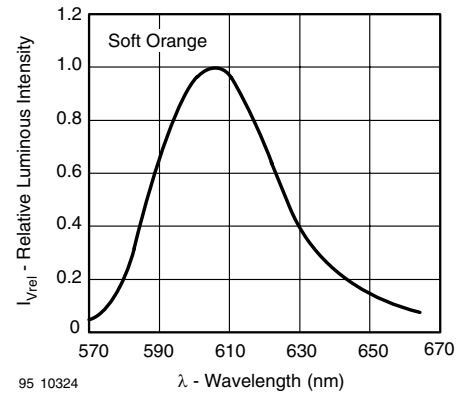


Figure 4. Relative Intensity vs. Wavelength

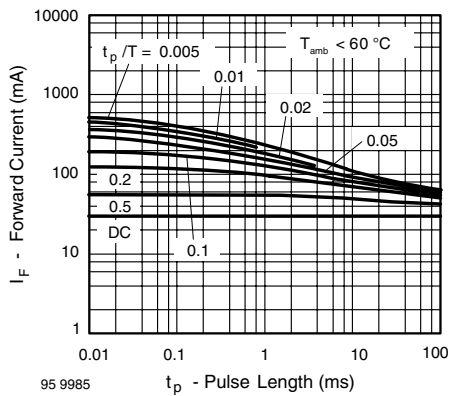


Figure 2. Forward Current vs. Pulse Length

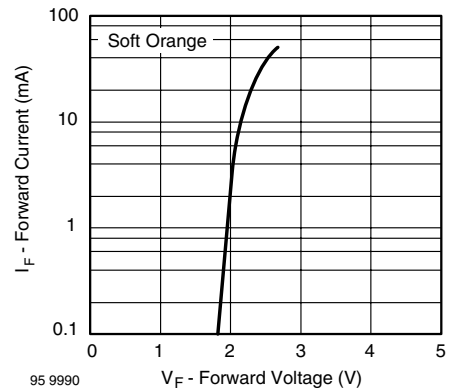


Figure 5. Forward Current vs. Forward Voltage

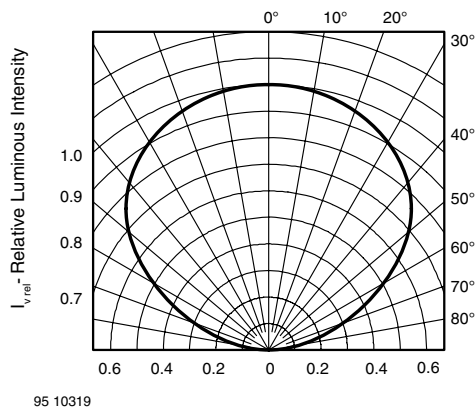


Figure 3. Rel. Luminous Intensity vs. Angular Displacement

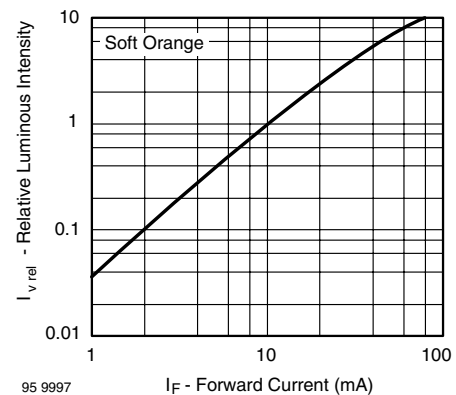


Figure 6. Relative Luminous Intensity vs. Forward Current

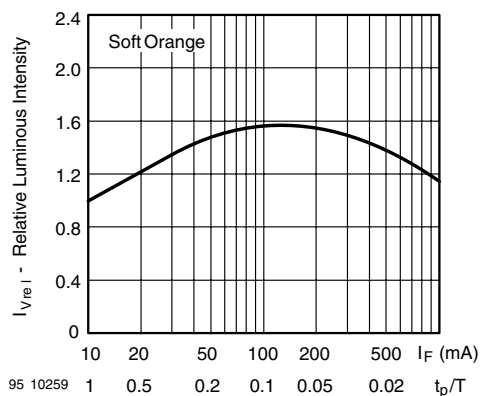


Figure 7. Rel. Lumin. Intensity vs. Forw. Current/Duty Cycle

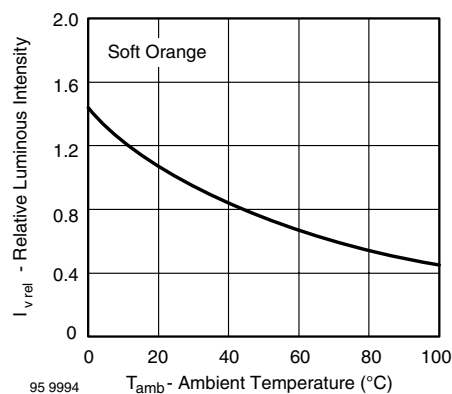
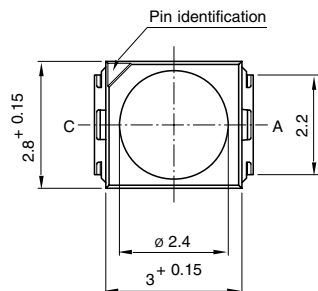
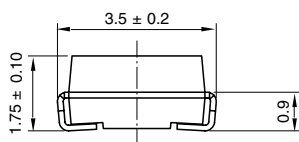


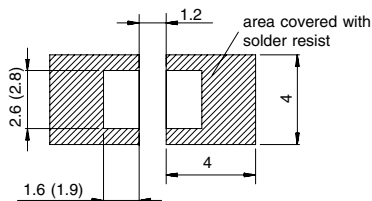
Figure 8. Rel. Luminous Intensity vs. Ambient Temperature

PACKAGE DIMENSIONS IN MM



Drawing-No. : 6.541-5025.01-4
Issue: 8; 22.11.05

Mounting Pad Layout

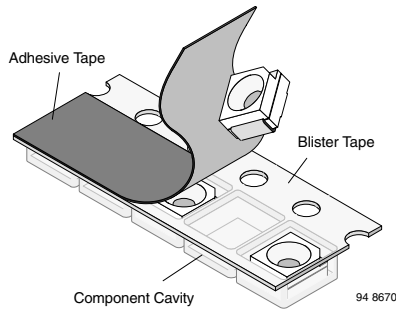


Dimensions: IR Reflow and Vaporphase
(Wave Soldering)

METHOD OF TAPING/POLARITY AND TAPE AND REEL

SMD LED (VLM.3 - SERIES)

Vishay's LEDs in SMD packages are available in an antistatic 8 mm blister tape (in accordance with DIN IEC 40 (CO) 564) for automatic component insertion. The blister tape is a plastic strip with impressed component cavities, covered by a top tape.



TAPING OF VLM.3...

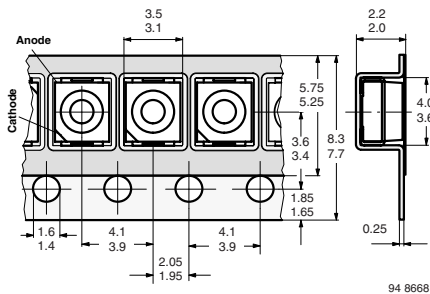


Figure 9. Tape dimensions in mm for PLCC-2

REEL PACKAGE DIMENSION IN MM FOR SMD LEDs, TAPE OPTION GS08 (= 1500 PCS.)

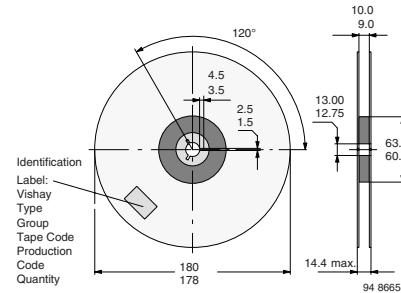


Figure 10. Reel dimensions - GS08

REEL PACKAGE DIMENSION IN MM FOR SMD LEDs, TAPE OPTION GS18 (= 8000 PCS.) PREFERRED

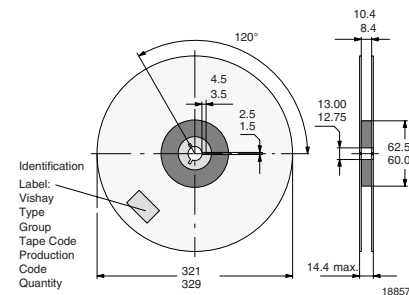


Figure 11. Reel dimensions - GS18

SOLDERING PROFILE

IR Reflow Soldering Profile for lead free soldering Preconditioning acc. to JEDEC Level 2a

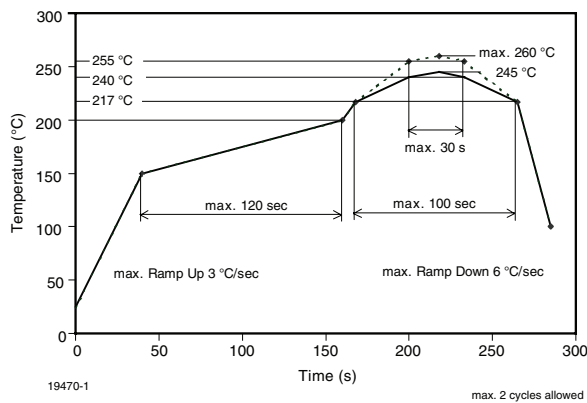


Figure 12. Vishay Leadfree Reflow Soldering Profile (acc. to J-STD-020C)

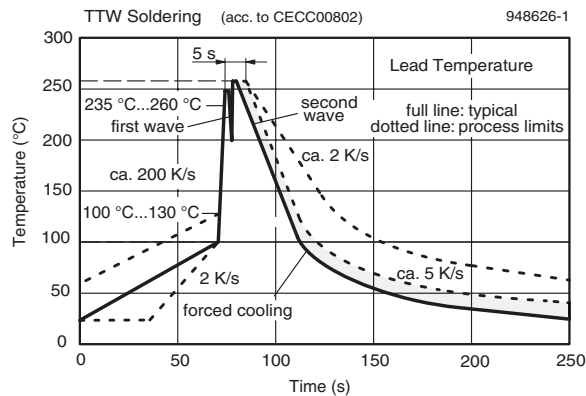
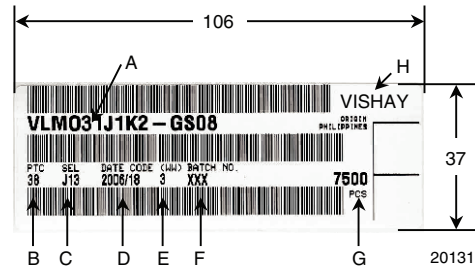


Figure 13. Double wave soldering of opto devices (all packages)

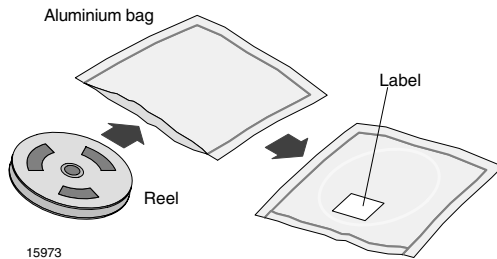
BARCODE-PRODUCT-LABEL



- A) Type of component
- B) Manufacturing Plant
- C) SEL - Selection Code (Bin):
e.g.: J1 = Code for Luminous Intensity Group
3 = Code for Color Group
- D) Date Code year/week
- E) Day Code (e.g. 3: Wednesday)
- F) Batch No.
- G) Total quantity
- H) Company Code

DRY PACKING

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.



FINAL PACKING

The sealed reel is packed into a cardboard box. A secondary cardboard box is used for shipping purposes.

RECOMMENDED METHOD OF STORAGE

Dry box storage is recommended as soon as the aluminium bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

- Storage temperature 10 °C to 30 °C
- Storage humidity ≤ 60 % RH max.

After more than 672 hours under these conditions moisture content will be too high for reflow soldering.

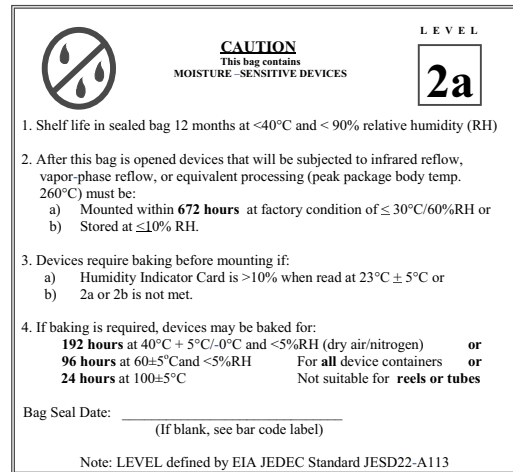
In case of moisture absorption, the devices will recover to the former condition by drying under the following condition:

192 hours at 40 °C + 5 °C/ - 0 °C and < 5 % RH (dry air/ nitrogen) or

96 hours at 60 °C + 5 °C and < 5 % RH for all device containers or

24 hours at 100 °C + 5 °C not suitable for reel or tubes.

An EIA JEDEC Standard JESD22-A112 Level 2a label is included on all dry bags.



Example of JESD22-A112 Level 2a label

ESD PRECAUTION

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the Antistatic Shielding Bag. Electro-Static Sensitive Devices warning labels are on the packaging.

VISHAY SEMICONDUCTORS STANDARD BAR-CODE LABELS

The Vishay Semiconductors standard bar-code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Semiconductors specific data.

Vishay Semiconductors

Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design
and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany



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